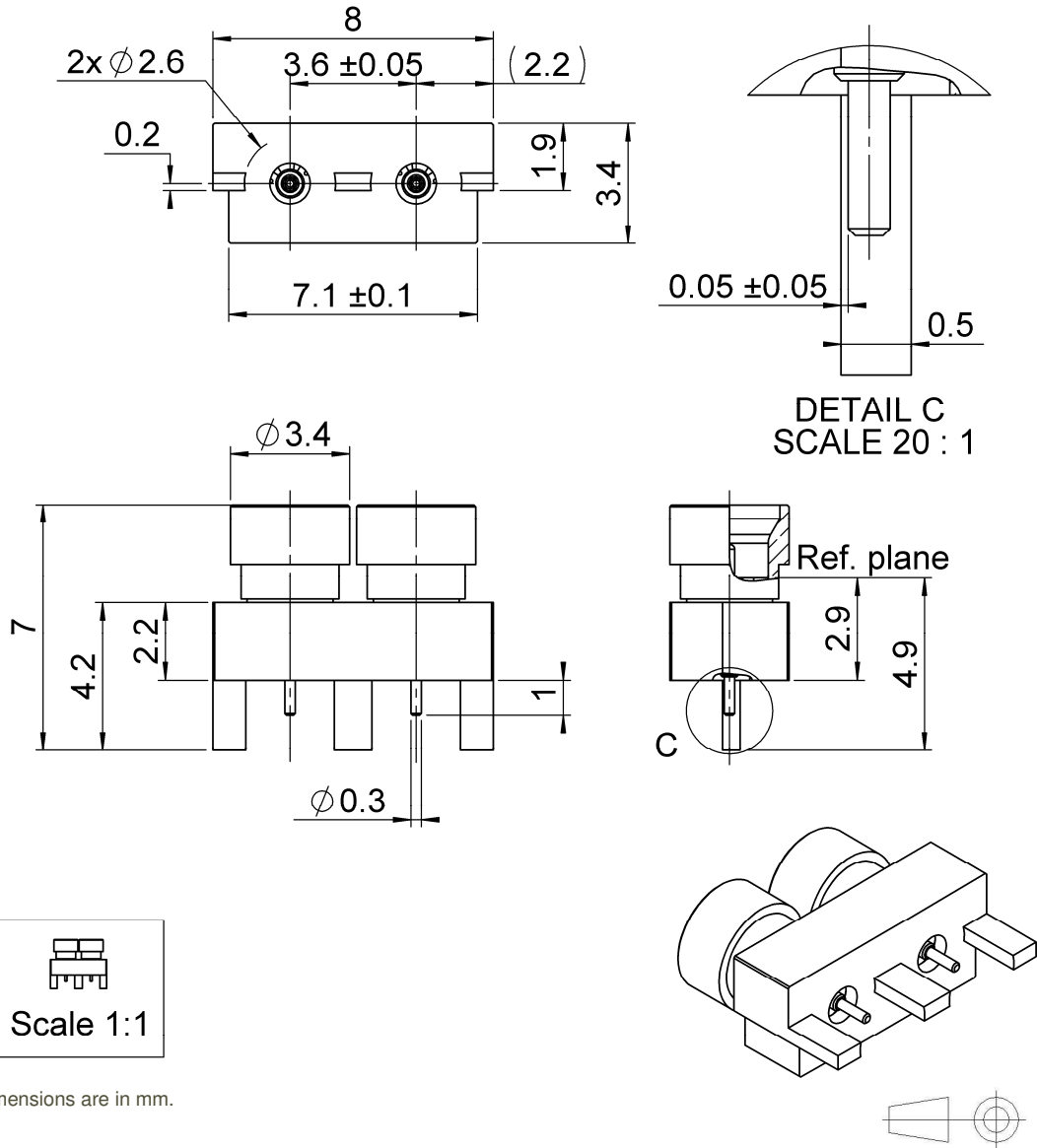


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All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	<b>BRASS</b>	<b>NPGR</b>
Center contact	<b>BERYLLIUM COPPER</b>	<b>NPGR</b>
Outer contact		
Insulator	<b>PEEK</b>	
Gasket		
Others parts		
-	-	-
-	-	-

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**PACKAGING**

Standard	Unit	Other
<b>500</b>	<b>Contact us</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-65</b>	GHz
VSWR	<b>0.0000</b>	x F(GHz) Maxi
Insertion loss	<b>0.1</b>	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	<b>NA</b>	- F(GHz)) dB Maxi
Voltage rating	<b>335</b>	Veff Maxi
Dielectric withstanding voltage	<b>500</b>	Veff mini
Insulation resistance	<b>5000</b>	M $\Omega$ mini
Center contact resistance	<b>6</b>	m $\Omega$ Maxi
Outer contact resistance	<b>2</b>	m $\Omega$ Maxi

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating End	<b>7</b>	N mini
Axial force – Opposite end	<b>7</b>	N mini
Torque	<b>NA</b>	N.cm mini
Mating force		
Engagement force - smooth bore	<b>18</b>	N Maxi
Disengagement force - smooth bore	<b>7</b>	N mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>500</b>	Cycles mini
Weight	<b>0.6200</b>	g

**ENVIRONMENTAL**

Operating temperature	<b>-65/+165</b>	$^{\circ}\text{C}$
Hermetic seal	<b>NA</b>	Atm.cm <sup>3</sup> /s
Panel leakage	<b>NA</b>	

**SPECIFICATION**  
**HUAWEI 14040556 V7.0**

**OTHER CHARACTERISTICS**

Assembly instruction: **NA**

Others:

\* **Coaxial transmission line only**

\* **VSWR:  $\leq 1.05$ , DC to 15GHz**

**$\leq 1.15$ , 15GHz to 25GHz**

**$\leq 1.22$ , 25GHz to 40GHz**

\***VSWR in application depends decisive on PCB layout**

**Vibration: MIL-STD-202, Method 204, Condition A**

**Shock: MIL-STD-202, Method 213, Condition A**

**Salt Spray: MIL-STD-202, Method 101, Condition B, 48h**

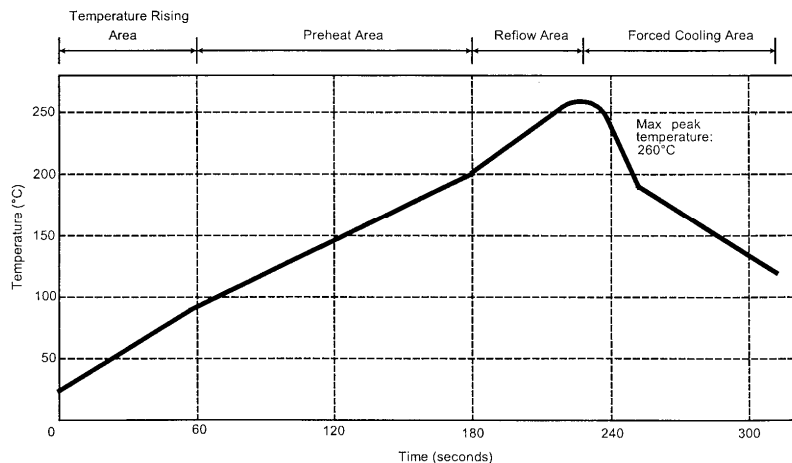
**Humidity-Temperature Cycling: MIL-STD-202, Method 106**

**Thermal Shock: MIL-STD-202, Method 107, Condition B**

## SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns ( 5.9 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow. Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

## TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec